

PAUL SCHERRER INSTITUT



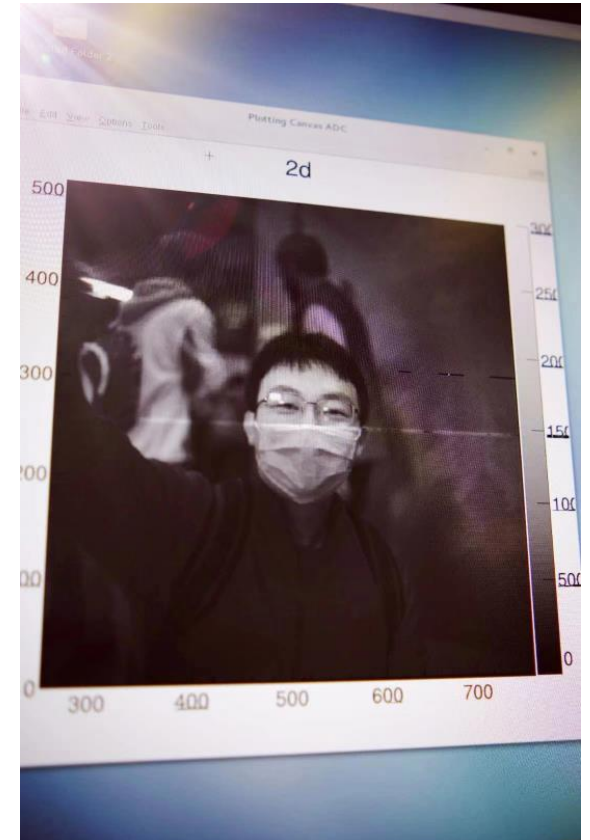
Xiangyu Xie :: Postdoc :: Photon Science Detector Group :: Paul Scherrer Institut

# Hybrid Pixel Detector development at PSI & Enhanced spatial resolution via DL for electron microscopy

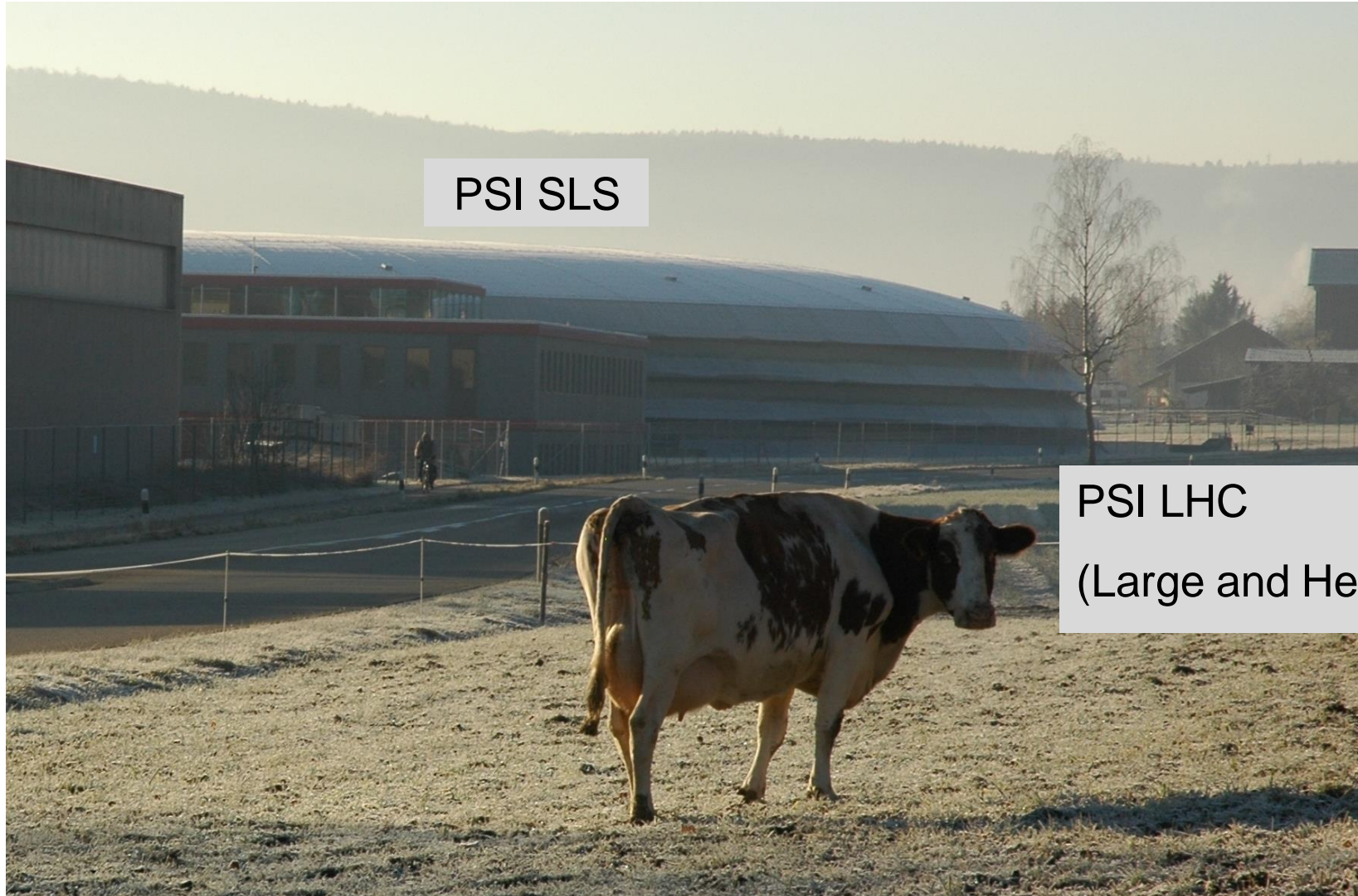
University of Science and Technology of China :: 2023.12.29

# About me ...

- Education
  - 2013-2017: BS, Physics, minor in Microelectronics, *University of Science and Technology of China*
  - 2017-2022: Ph.D., Experimental Particle Physics, *University of Science and Technology of China*
- Work experience
  - 2022-present: postdoctoral researcher, Photon Science Division detector group, *Paul Scherrer Institut*
- Research interest
  - Detector R&D, deep learning for detectors



- Hybrid pixel detector development for photon science at PSI
  - PSI and Photon Science detector group
  - Hybrid pixel detector developments at PSI
- Enhanced spatial resolution of MÖNCH via deep learning for electron microscopy
  - Sample preparation
  - Neural network design
  - Results evaluation

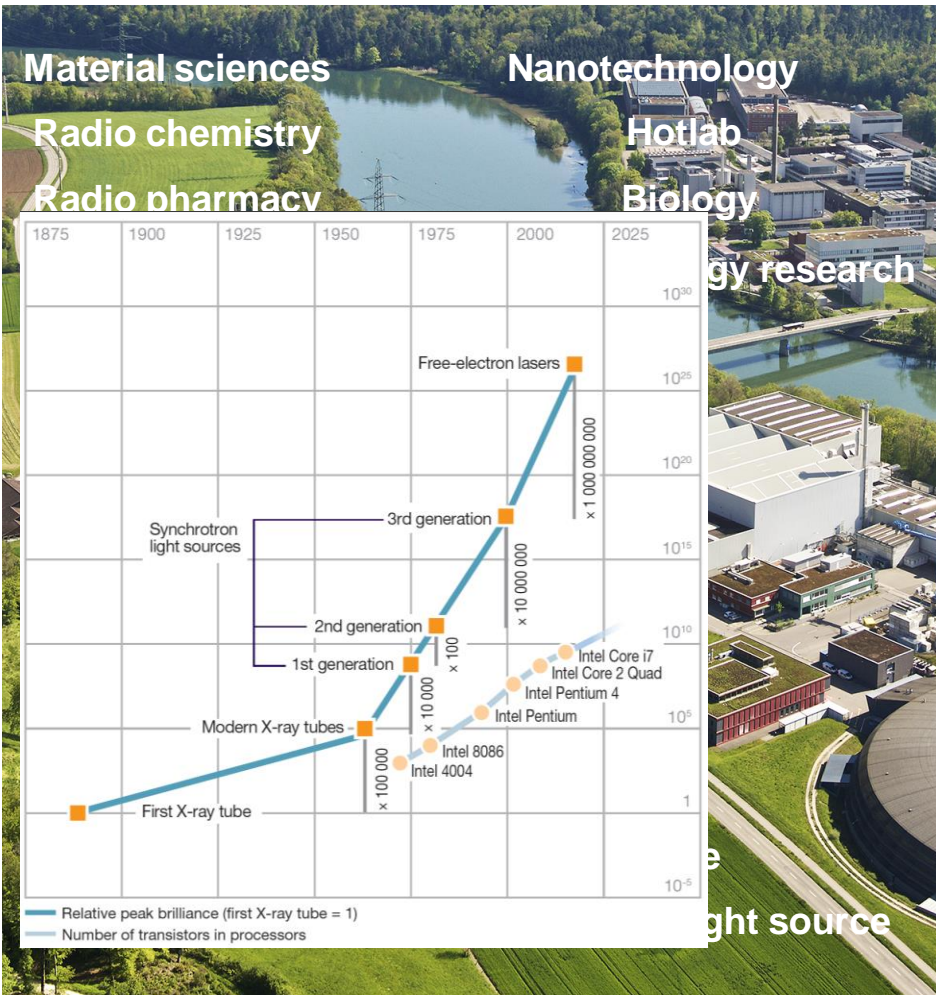


PSI SLS

PSI LHC

(Large and Heavy/Holy Cow)

(Won 3<sup>rd</sup> prize in  
SLS photo contest  
Courtesy: Roberto)



- Paul Scherrer Institut, PSI, is the largest research center for natural and engineering sciences in Switzerland (2100 employees), belongs to the ETH domain, federal funded
- PSI is running Switzerland's large research facilities (neutrons, protons, muons, X-Rays)



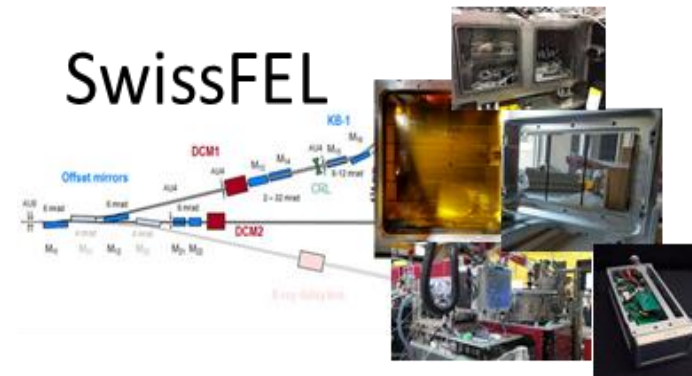
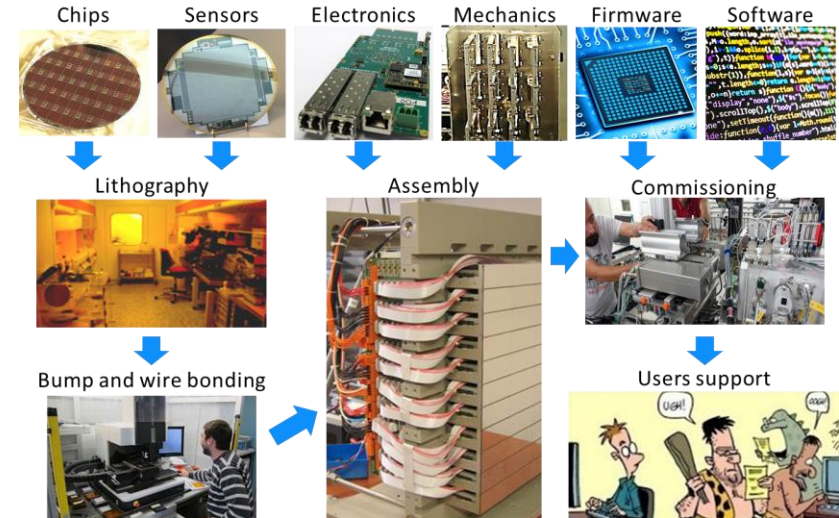
XFEL: SwissFEL, 740m long

Synchrotron: SLS Swiss Light Source

2.4 GeV, 288 m circumference, ~20 beamlines

# Photon Science Division detector group

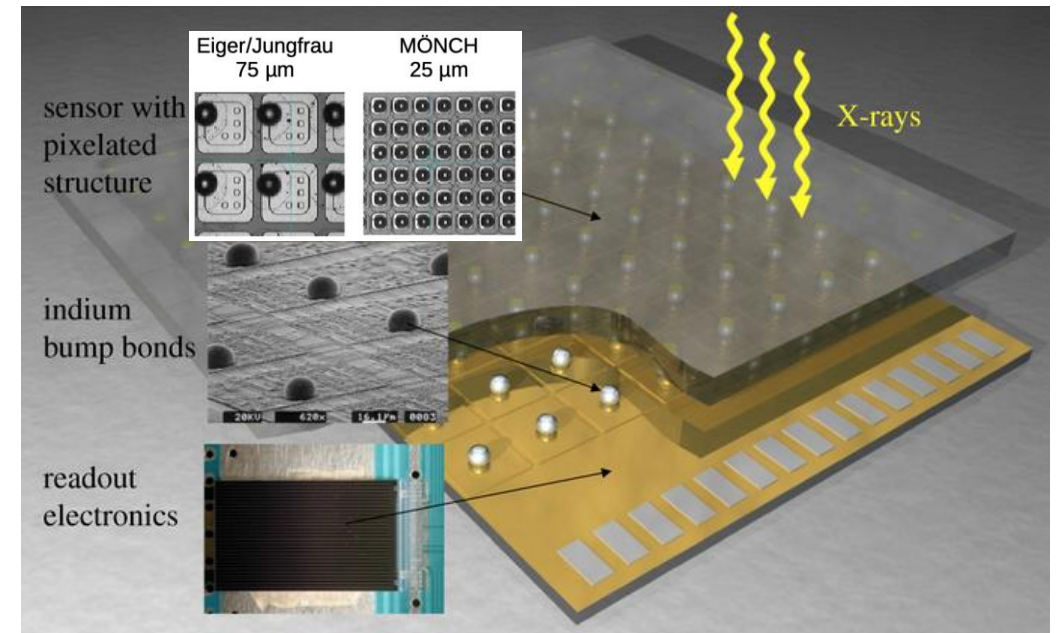
- Develop detectors for the SLS and SwissFEL
  - Detector R&D
  - Design and production
  - Characterization and commissioning
- Other applications: electron microscopy



# Hybrid Pixel Detector

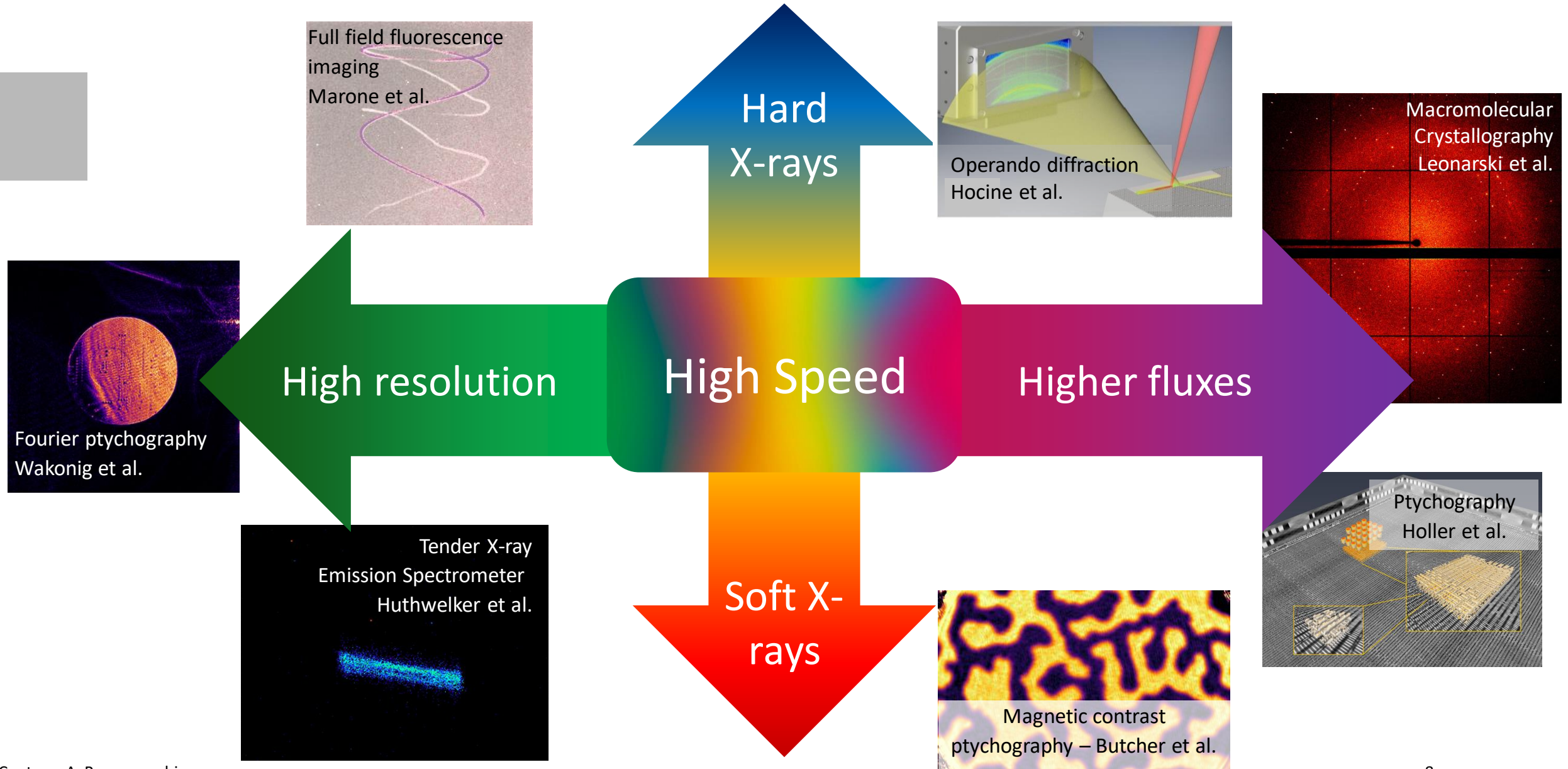
- Semiconductor sensor
  - Direct conversion
- Versatile readout ASICs
  - Fast signal processing
  - Fast readout
  - Radiation hardness
- Bump/Wire-bonding
  - Minimum pixel pitch  $\approx 25 \mu\text{m}$
  - Noise due to input capacitance

## Hybrid pixel detector



- Sensor & ASICs can be optimized independently
- Can be customized according to applications

# Challenges





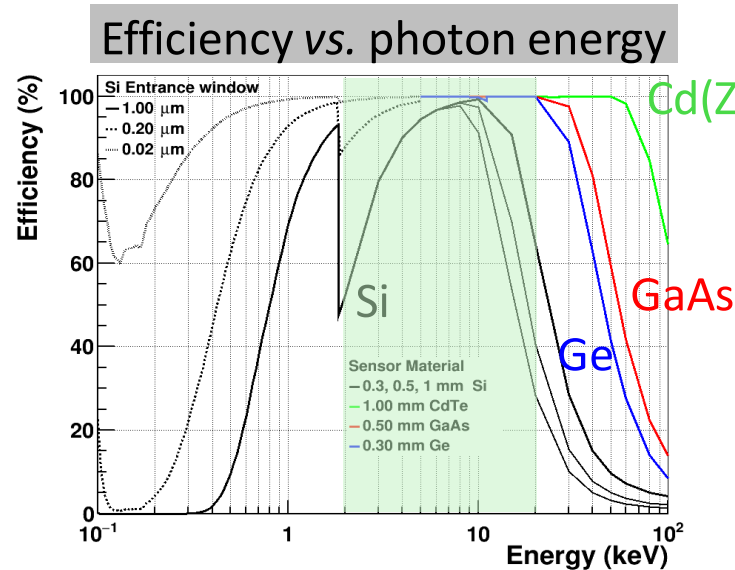
- Inadequate silicon sensor performance at “low” and “high” photon energies

## Soft X-rays (250 eV – 2 keV):

- low quantum efficiency of Si

## Two technological developments

- thin entrance window
- inverse Low Gain Avalanche Diode (iLGAD) sensor



## High-energy photons (> 20 keV):

- limited stopping power of Si

## Material under investigations

- CdZnTe
- CdTe
- GaAs

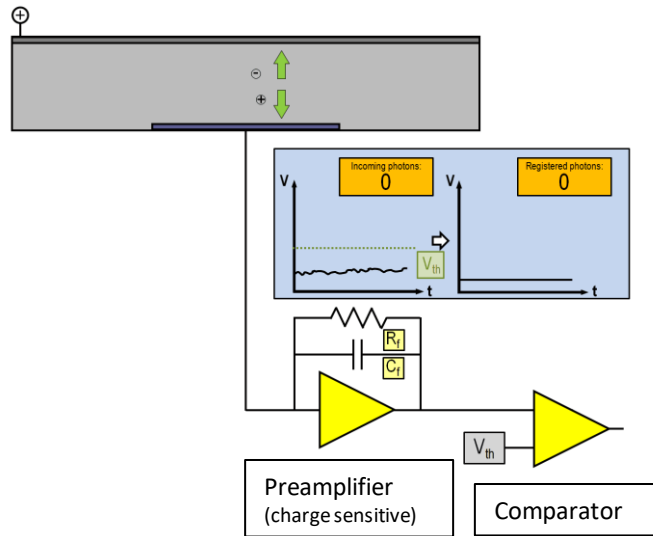
## Performance of high-Z sensors

	Energy resolution	Stability	Afterglow	Dark current	Availability
High flux -500V CdZnTe	😊	😊	😊	😊	😞
Schottky -500V CdTe	😐	😞	😞	😊	😊
GaAs:C -300V	😐	😐	😞	😞	😊

# Photon counting vs. Charge integrating detectors

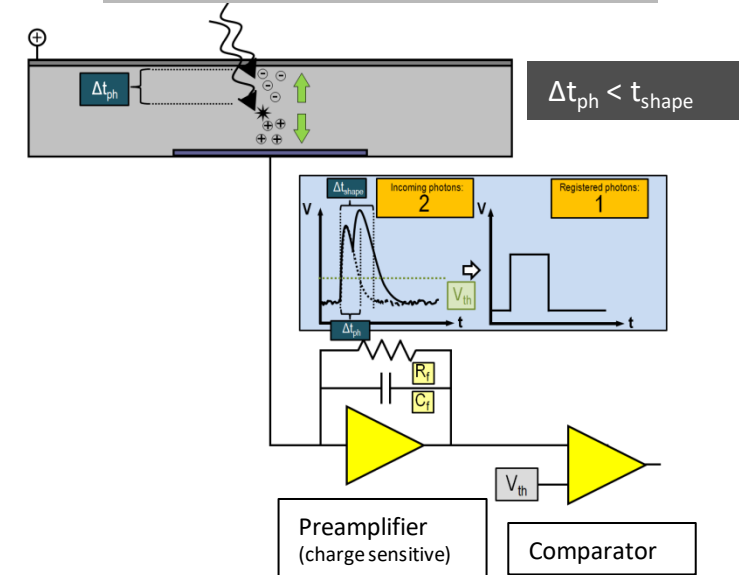
## Single photon detection

Single Photon Counting

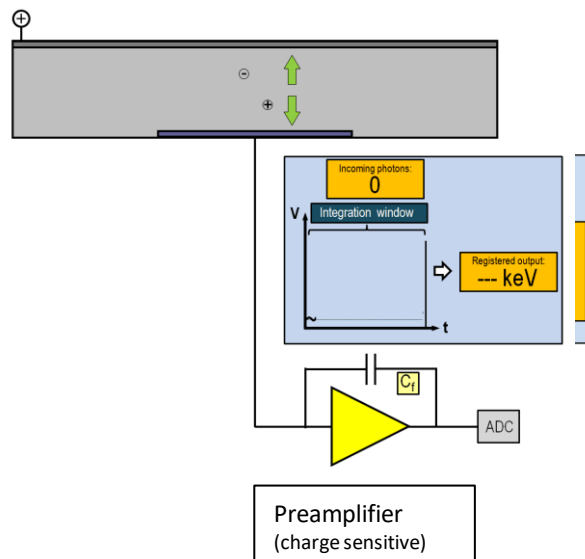


- + Readout of digital info
- + 'Noise free' operation
- + (Almost) unlimited dynamic range
- Minimum detectable energy
- Count-rate limitation (pile-up)

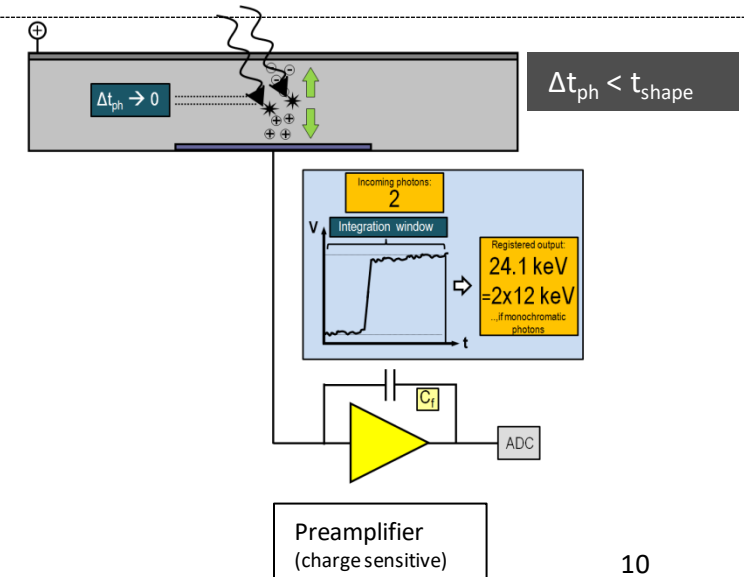
## Multiple photons




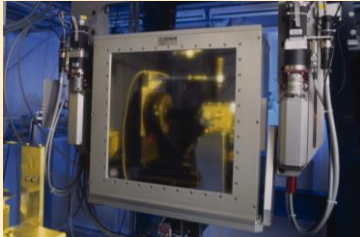
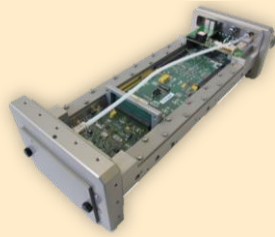

Charge Integrating



- + Energy for each photon  
(Low flux, Polychromatic)
- + Practically no count-rate limitation  
(High flux, Dynamic Gain)
- + Measurement of charge sharing  
(Position interpolation)
- Calibration procedure challenging
- Integration of leakage current




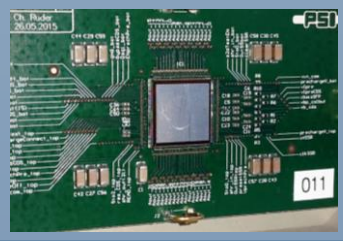


# Detector portfolio: Photon counting

	MYTHEN-3	PILATUS	EIGER	MATTERHORN
				
<b>Technology</b>	UMC 110 nm	UMC 250 nm	UMC 250 nm	UMC 110 nm
<b>Status</b>	Modules available	Commercially available <sup>1</sup>	Commercially available <sup>1</sup>	Prototyping phase
<b>Pixel size</b>	50 $\mu\text{m}$ (Strips)	172 x 172 $\mu\text{m}^2$	<b>75 x 75 <math>\mu\text{m}^2</math></b>	<b>75 x 75 <math>\mu\text{m}^2</math></b>
<b>Maximum system size</b>	120° (=48 modules)	<b>6M</b> (=42 x 43 $\text{cm}^2$ )	<b>9M</b> (=23 x 23 $\text{cm}^2$ )	
<b>Minimum threshold</b>	< 4 keV	< 2 keV	< 2.5 keV	
<b>Count rate capability</b>	>2 MHz/Strip (10% deviation, Standard)	0.5-1.0 MHz/Pixel (10% deviation)	0.2-0.7 MHz/Pixel (10% deviation)	
<b>Maximum frame rate</b>	<b>300 kHz (8-bit)</b>	300 Hz/Module	<b>23 kHz (1-bit)</b>	

<sup>1</sup>) PILATUS and EIGER are commercially available at Dectris.

# Detector portfolio: Charge integrating

	GOTTHARD-2	AGIPD <sup>1</sup>	JUNGFRAU	MÖNCH
				
<b>Technology</b>	UMC 110 nm	IBM 130 nm	UMC 110 nm	UMC 110 nm
<b>Status</b>	Modules available	Modules available	Modules available	Prototyping phase
<b>Pixel size</b>	50 / 25 $\mu\text{m}$ (Strips)	200 x 200 $\mu\text{m}^2$	<b>75 x 75 <math>\mu\text{m}^2</math></b>	<b>25 x 25 <math>\mu\text{m}^2</math></b>
<b>Maximum system size</b>	10 / 20 ASICs	1Mpixel	16Mpixel	
<b>Noise (r.m.s.)</b>	$\sim 270 e^-$ ENC @ 4.5 MHz	$< 322 e^-$ ENC $< 214 e^-$ ENC (HG)	<b><math>&lt; 100 e^-</math> ENC (G0)</b> <b><math>&lt; 55 e^-</math> ENC (HG0)</b>	
<b>Dynamic range</b>	$< 1 \cdot 10^4 \times 12.4 \text{ keV}$ (3 gain stages)	$< 1 \cdot 10^4 \times 12.4 \text{ keV}$ (3 gain stages)	$< 1 \cdot 10^4 \times 12.4 \text{ keV}$ (3 gain stages)	
<b>Maximum frame rate</b>	<b>400 kHz (cont.)</b> <b>4.5 MHz (burst)</b>	<b><math>&lt; 5 \text{ MHz}</math> (burst*)</b> <b>* 352 frames</b>	<b>2.4 kHz (cont.)</b> <b><math>&lt; 1 \text{ MHz}</math> (burst)</b>	

<sup>1)</sup> Common development with University of Bonn, University of Hamburg and DESY

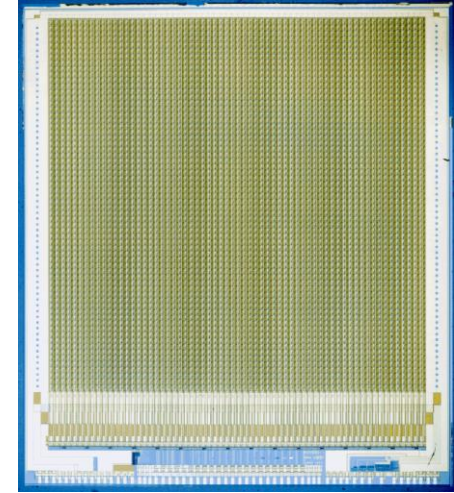
# The birth of hybrid pixel detectors for Photon Science

# CERN

Alice1LHCb



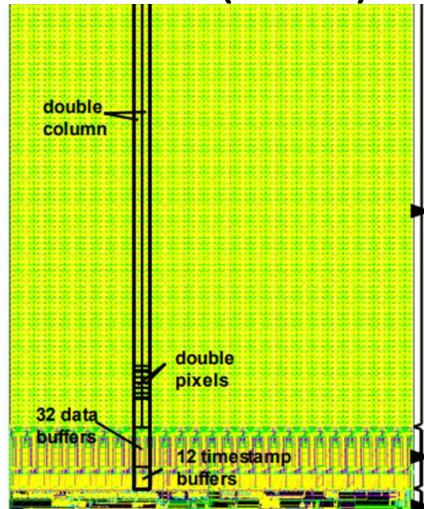
Medipix 1



M. Campbell  
E. Heine  
X. Llopart

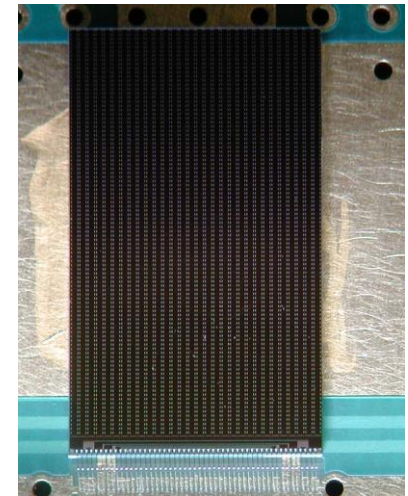
# PSI

PSI46 (CMS)



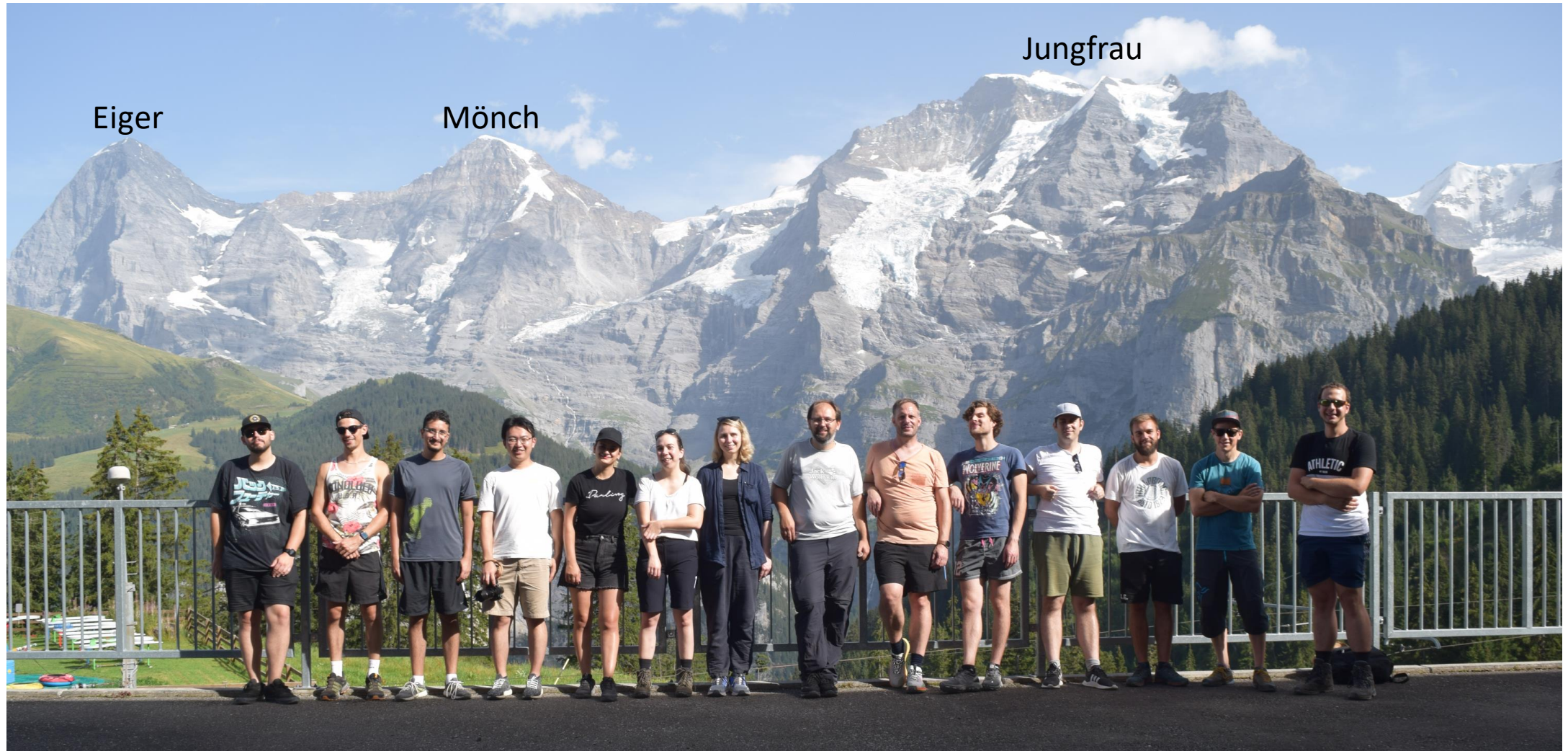
R. Horisberger  
F. Van Der Veen  
C. Broennimann

Pilatus I



# Group members

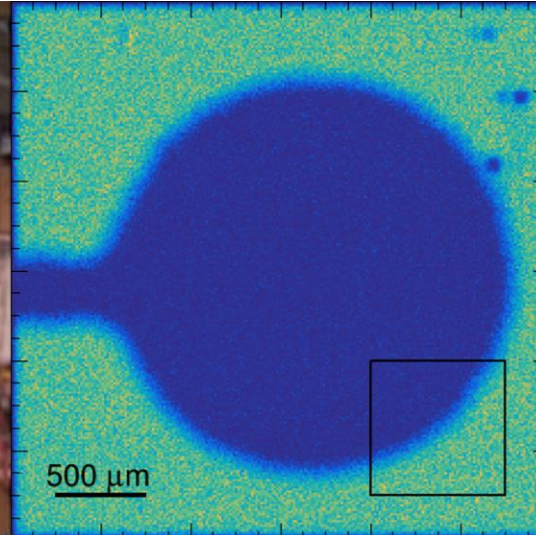
August 2023



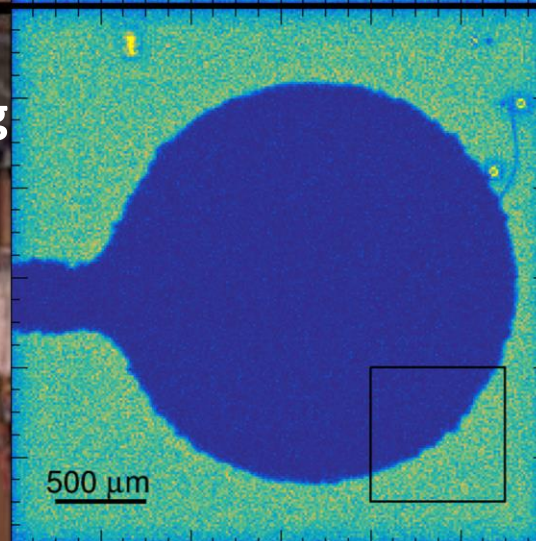
Missing: Anna, Bernd, Jiaguo, Aldo, Christian, Carlos, Davide, Dhanya, Roberto, Konstantinos...

# Outline

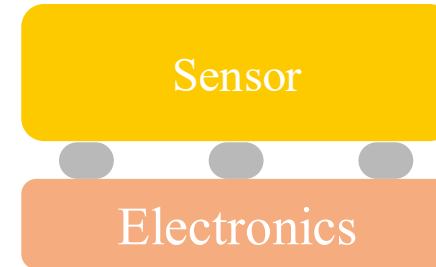
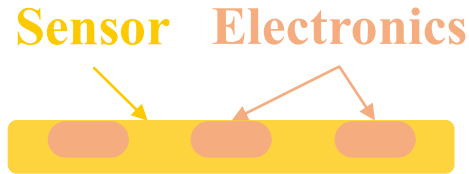
- Hybrid pixel detector
  - PSI and the PS
  - Hybrid pixel de
- Enhanced spatial
  - Sample prepar
  - Neural networ
  - Results evalua



electron microscopy

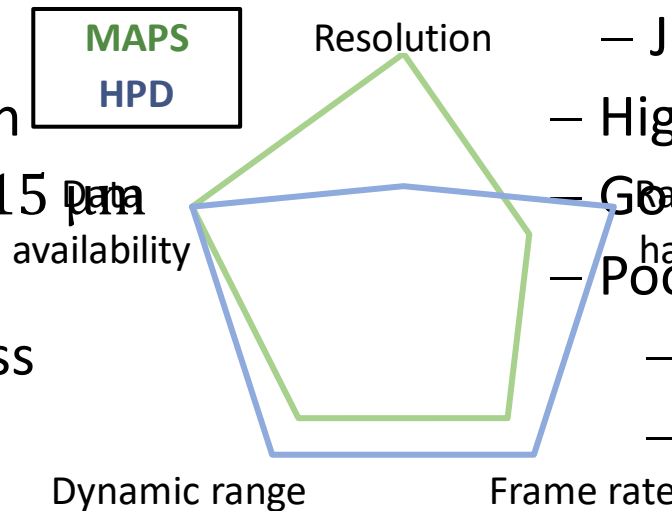


# Direct Electron Detector for Electron Microscopy, the “resolution revolution”



- Monolithic Active Pixel Sensor (MAPS)
  - Widely applied for (cryo-)imaging and diffraction measurements
  - K2, Falcon...
  - Good spatial resolution
  - Pixel size usually  $< 15 \mu\text{m}$
  - Limited frame rate
  - Poor radiation hardness

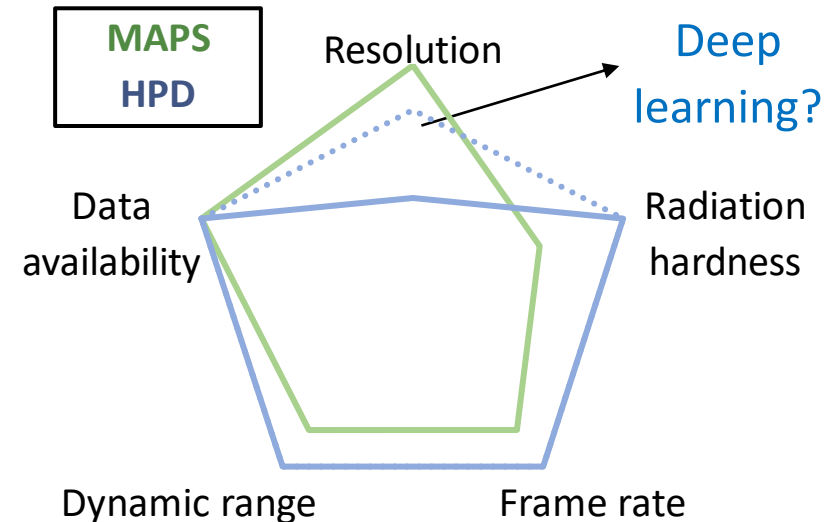
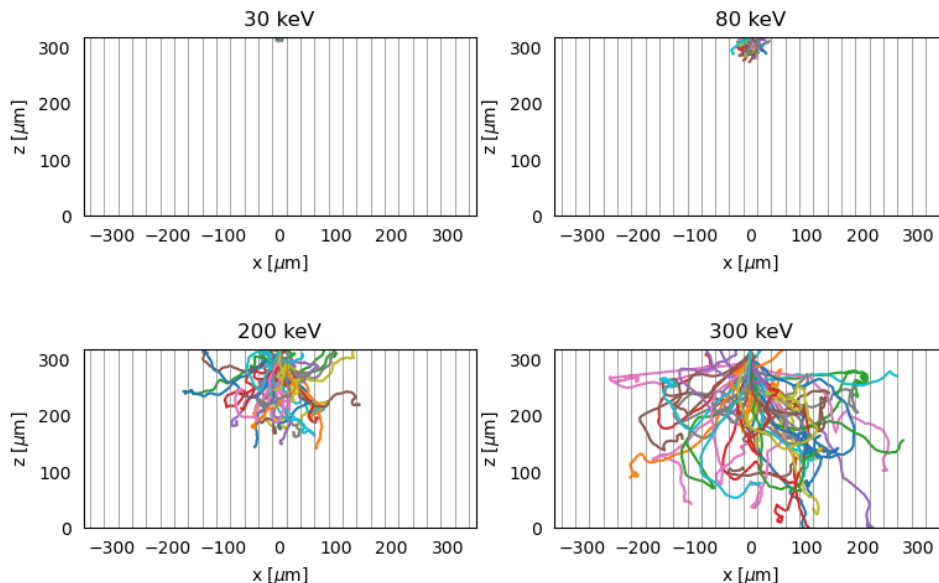
- Hybrid Pixel Detector (HPD)
  - Getting popular for diffraction measurements
  - JUNGFRAU, Medipix...
  - High dynamic range and frame rate
  - Good radiation hardness
  - Poor resolution
  - Large pixel size usually  $\geq 55 \mu\text{m}$
  - Electron multiple scattering





# MÖNCH, towards a universal detector for diffraction and imaging

- MÖNCH, a HPD with much smaller pixel
  - **25  $\mu\text{m}$**  pitch size
  - $400 \times 400$  pixels per tile
  - Charge integration, 14 bit, up to 6 kHz
- Lateral track due to multiple scattering
  - Poor resolution for  $e^-$  with  $E > 80\text{keV}$
- **Deep learning** to reconstruct position
  - From the complex pattern to learn
  - Nature of energy deposition
  - Charge diffusion
  - Aim at subpixel resolution



- Funded as a Swiss Data Science Center(SDSC) project

## SDSC hub @ PSI



Dr. Carl  
Remlinger



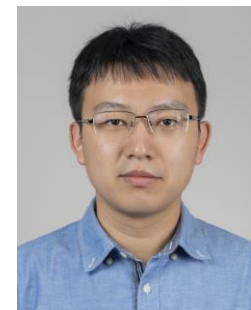
## PSI

### Electron Microscope Facility group



## PSI

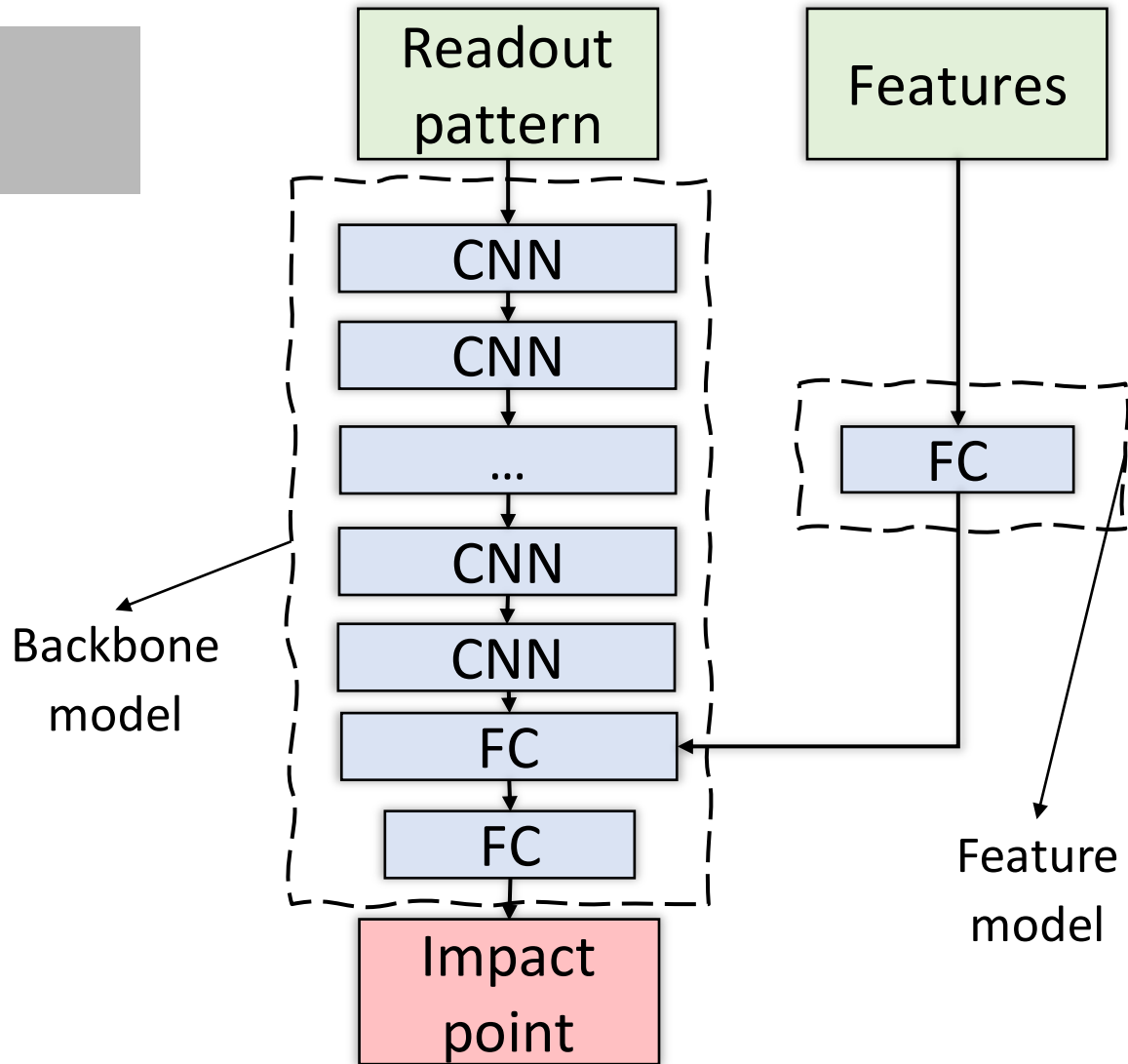
### Photon Science Division Detector group



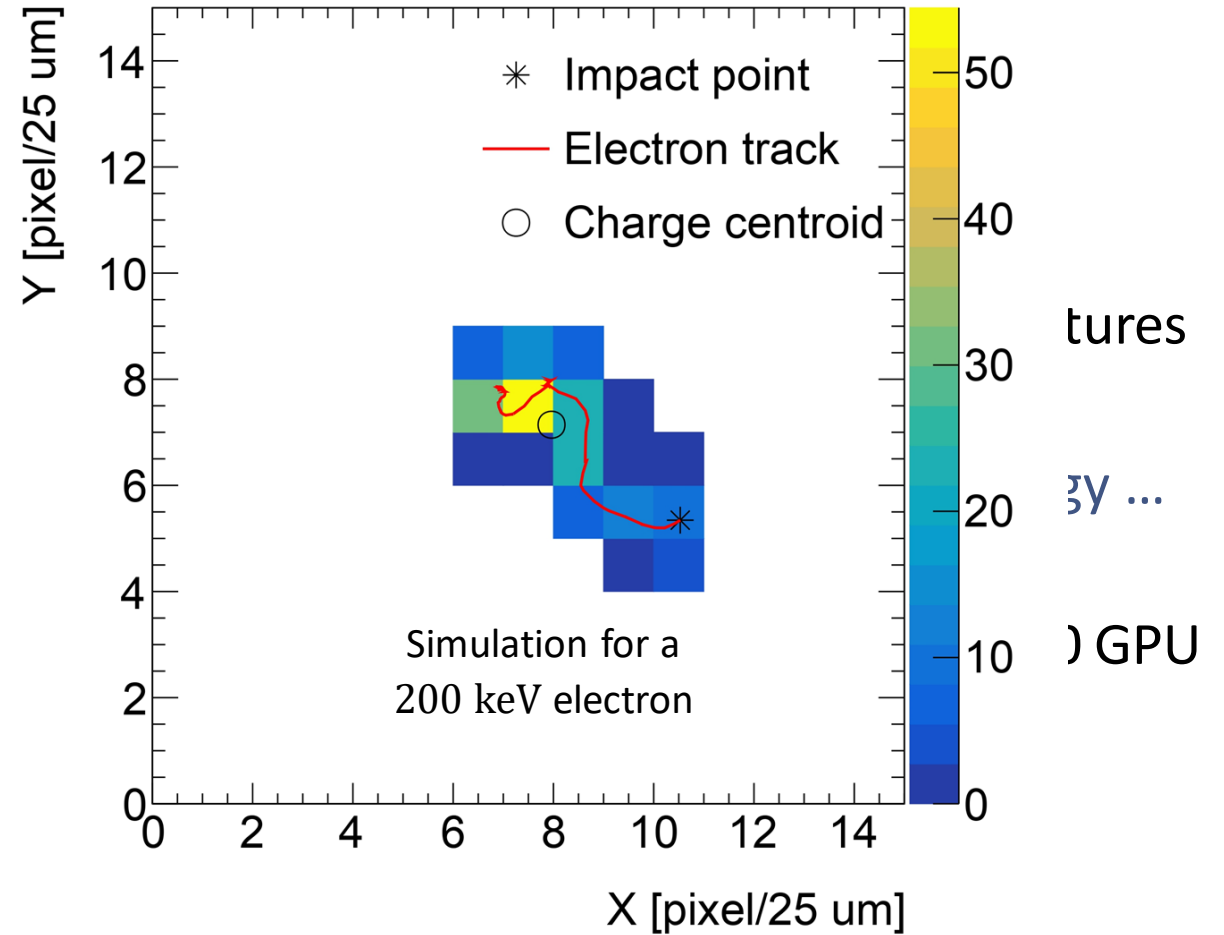
# Project overview

- Deep learning development
  - Neural network candidate models
    - A baseline model (results discussed in this report)
    - Auto-encoder
    - ...
  - Samples preparation
    - Simulation and experimental
    - Key: the ground truth impact point
- Characterization
  - Spatial resolution
  - Detective quantum efficiency
  - Standard sample imaging
- Deployment & dissemination
  - Data processing pipeline(WIP)

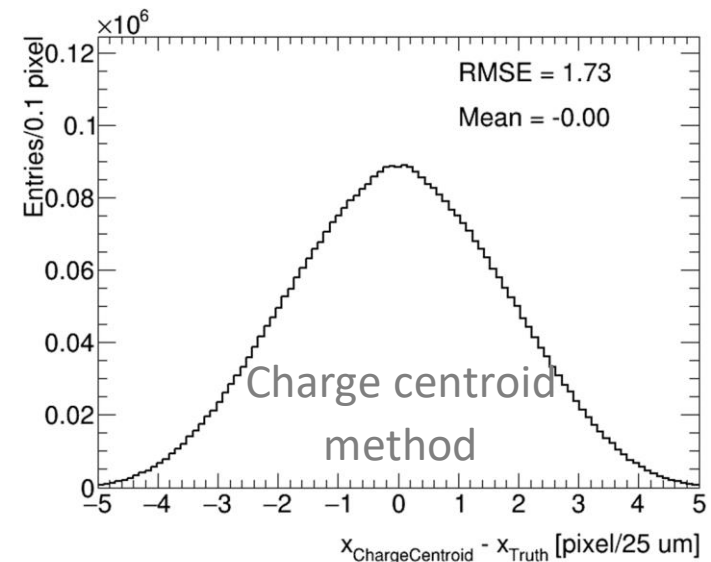
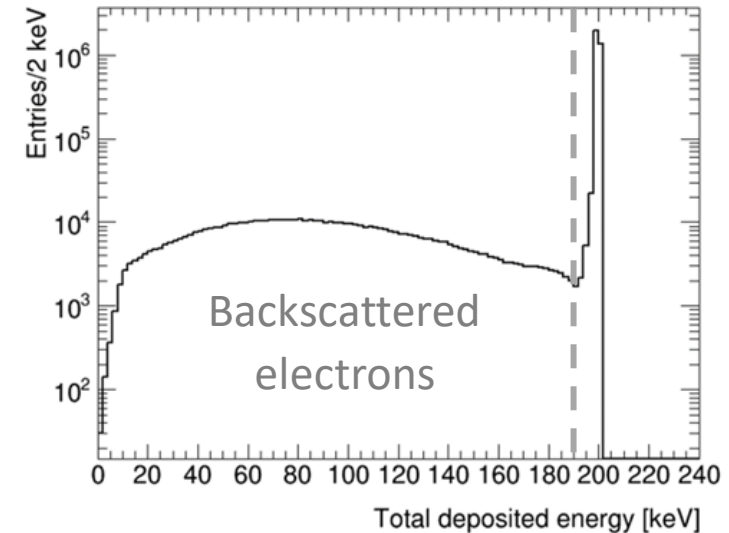
# Baseline neural network model



- **Input:** readout pattern and features

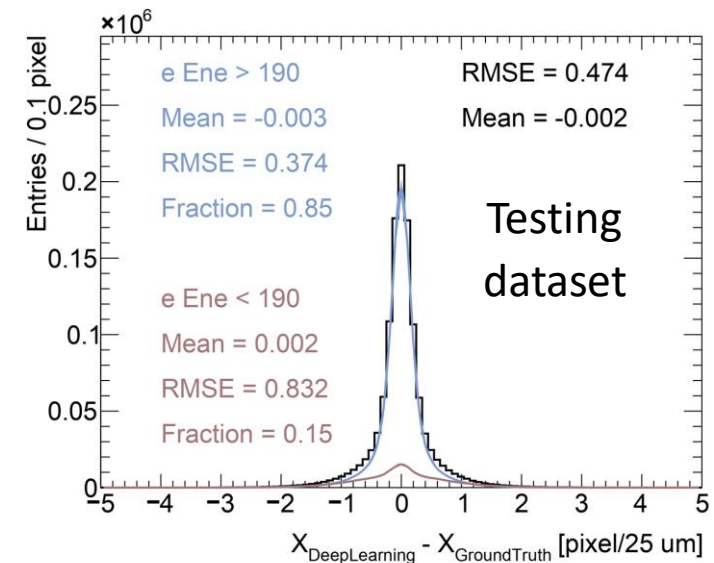
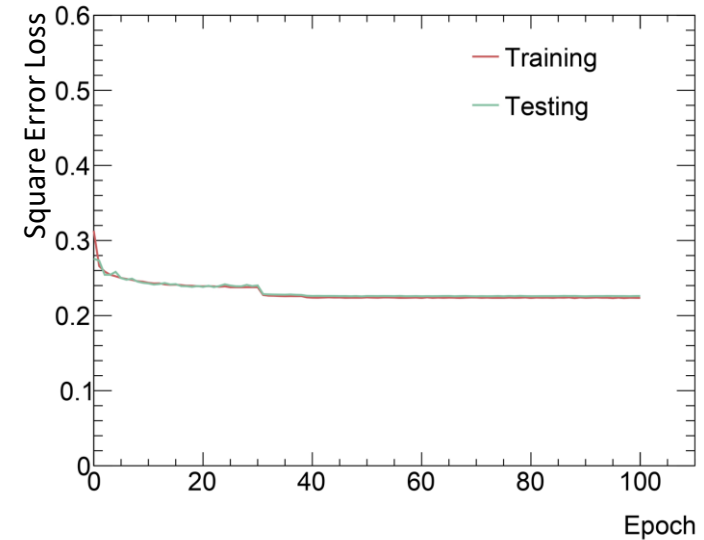


- Simulation setup
  - Geant4 + charge diffusion model
  - 320  $\mu\text{m}$  silicon sensor
  - $V_{\text{bias}} = 90 \text{ V}$
  - Start with 200 keV electrons
  - Total samples: 4M
    - 70%/30% for training/testing
- Simulation analysis
  - $\sim 15\%$  backscattered electrons
  - Charge centroid gives  $\sigma_x = 1.73$  pixel



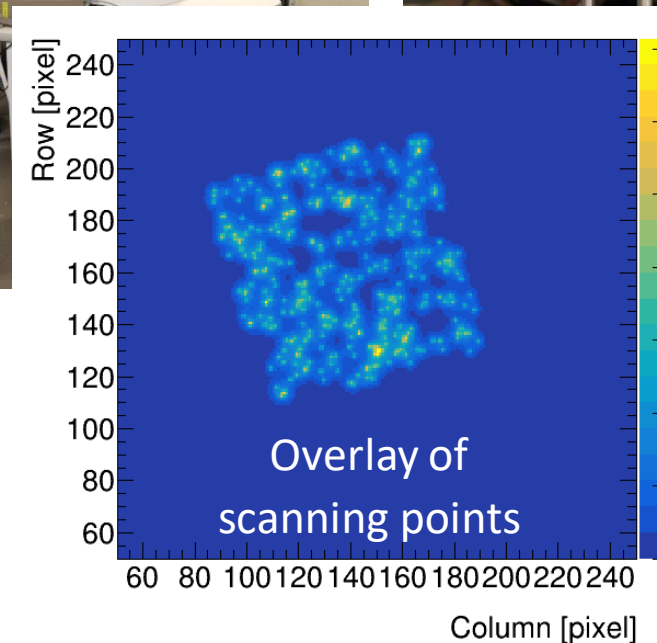
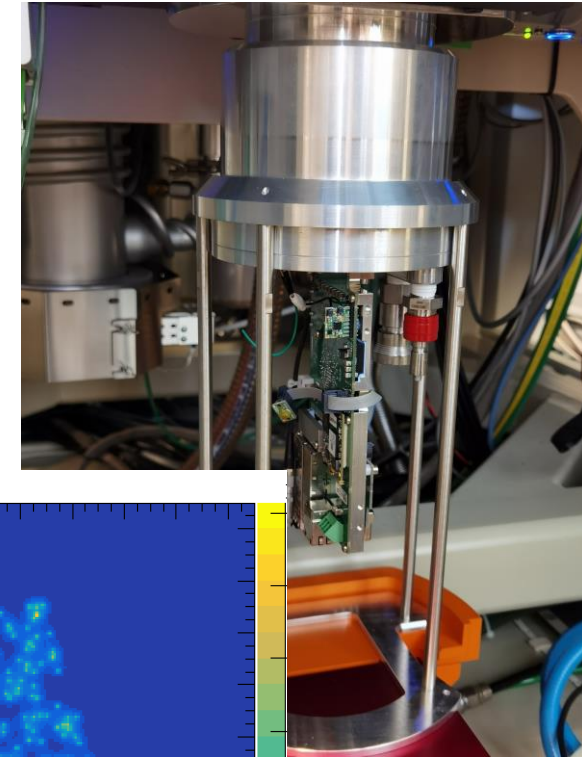
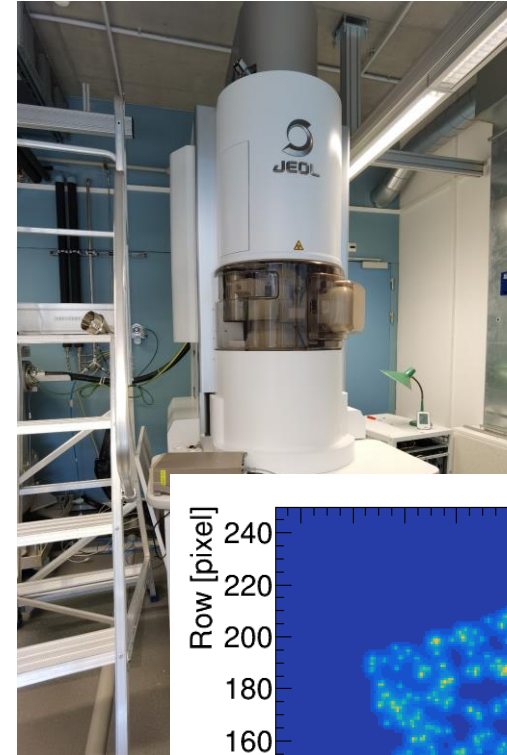
# Simulation-based: training and results

- Training setup
  - 100 epochs/iterations
  - Data augmentation
    - Rotation and flipping
    - Training label smoothing
    - Synthetic noise ( $\sigma = 0.18$  keV)
- Simulation-based results
  - No significant overfitting
  - Deep learning gives  $\sigma_x = 0.47$  pixel
  - Fully deposited  $e^-$ :  $\sigma_x = 0.37$
  - Backscattered  $e^-$ :  $\sigma_x = 0.83$

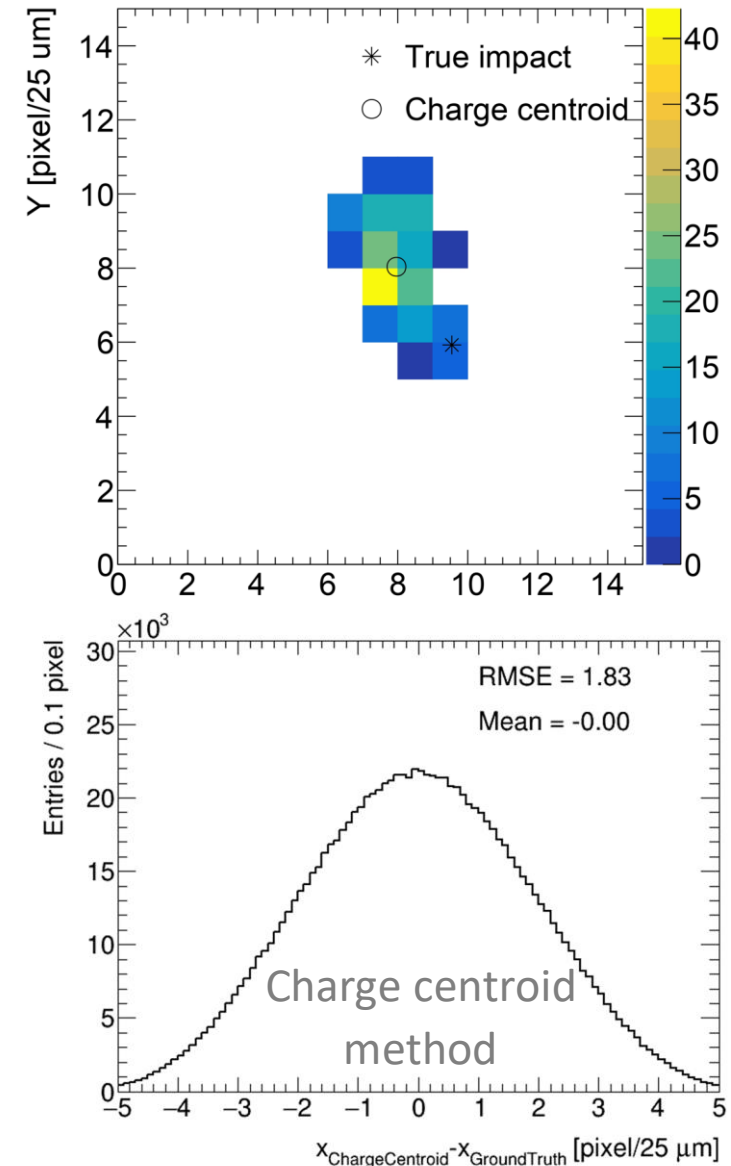


# Experiment-based: data taking setup

- EM: Jeol JEM ARM200F
  - 200 keV beam
  - Customized alignments
  - Narrow beam ( $\sim\mu\text{m}$ )
- Detector: MÖNCH v0.3
  - One tile;  $400 \times 400$  pixels
  - $V_{\text{bias}} = 90 \text{ V}$
- Ground truth impact points obtaining
  - EM randomly scans with longer dwell time ( $\sim\text{s}$ )
  - 430 scan points  $\times$  10,000 frames
  - **Unbiased ground truth position:  $\bar{x}, \bar{y}$**



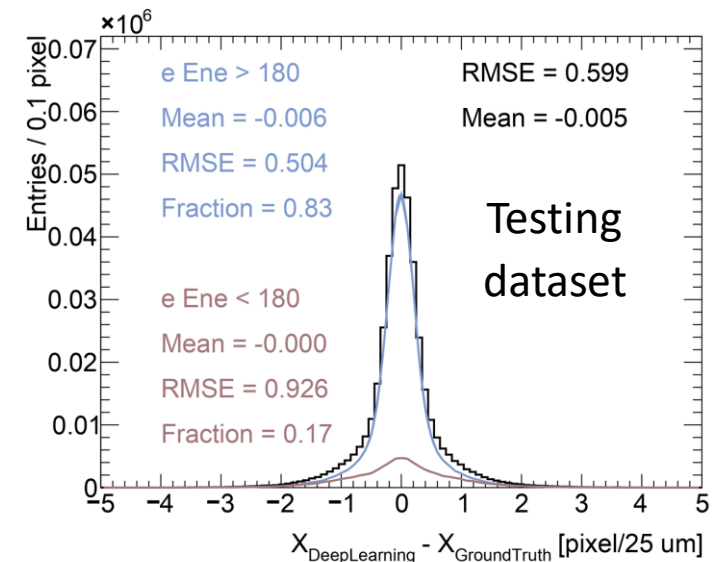
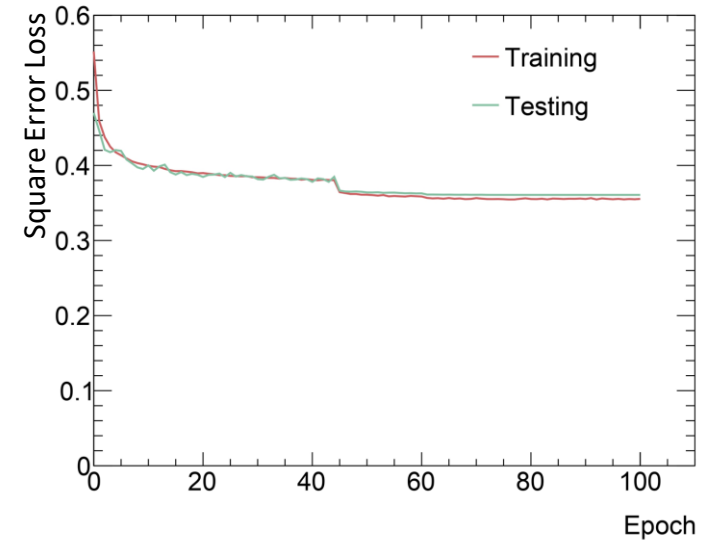
- Frame level
  - Mask malfunction region
  - Pedestal subtraction
  - Energy conversion
- Cluster finding and selection
  - Adjacent pixels over a threshold of  $5 \times \text{Noise} \approx 0.9 \text{ keV}$  (g2\_lc\_hg mode)
  - $20 \text{ keV} < E_{\text{cluster}} < 220 \text{ keV}$
  - Outlier filtered
- Total samples:  $\sim 1\text{M}$ 
  - Charge centroid gives  $\sigma_x = 1.83 \text{ pixel}$





# Experiment-based: deep learning results

- Training setup
  - 100 epochs
  - Data augmentation
    - Rotation and flipping
    - Training label smoothing
- Experiment-based results
  - No significant overfitting
  - Deep learning give  $\sigma_x = \mathbf{0.60 \text{ pixel}}$
- Independent knife-edge measurements
  - Sample processed by the trained model
  - Edge spread function gives  $\sigma_x = \mathbf{0.58 \text{ pixel}}$



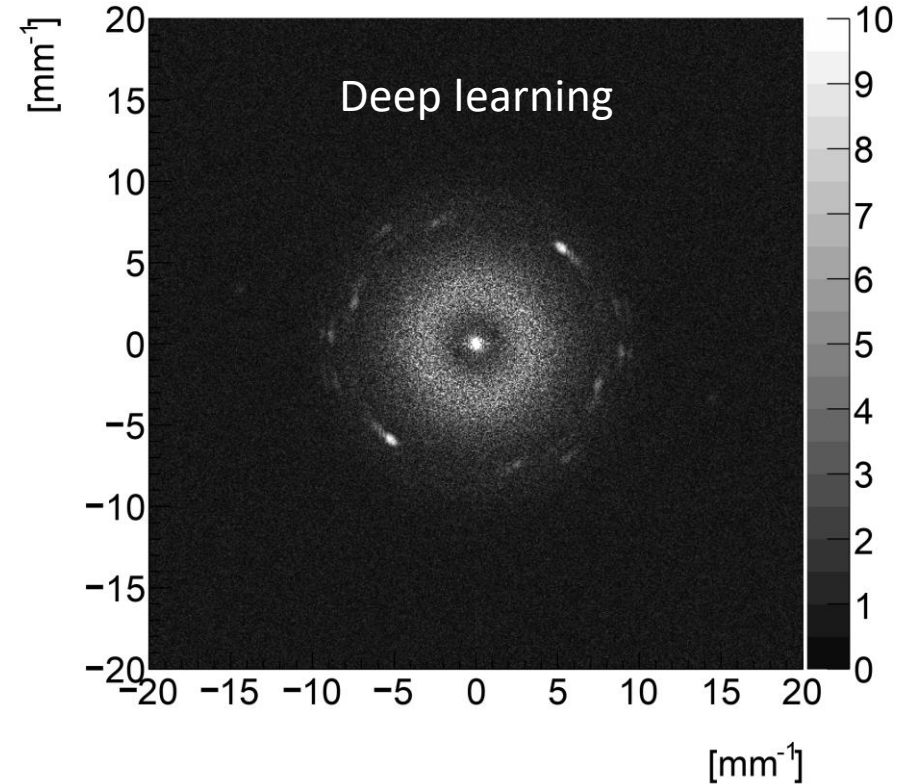
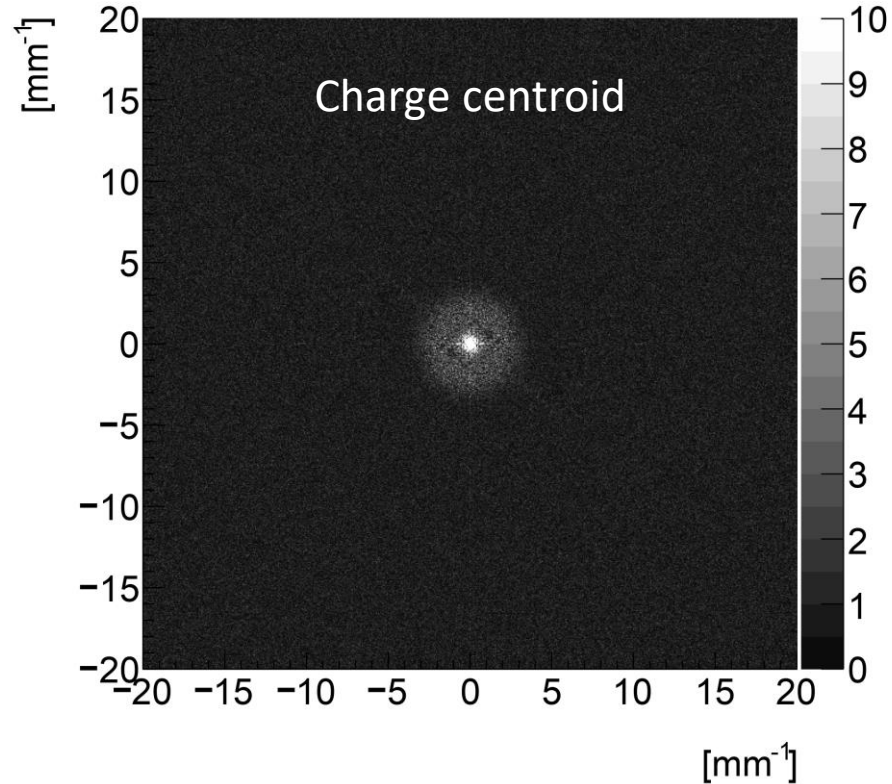
# Preliminary MTF and DQE results (200 keV)

$$\text{MTF}(\omega) = \mathcal{F}[\text{PSF}(x)]$$

$$\text{DQE}(\omega) = \text{MTF}^2(\omega) \frac{d_n^2}{n\text{NPS}(\omega)}$$

Flux =  $\sim 10 e^-/\text{s}/\text{pixel}$

- TEM sample with continuous carbon and gold nanoparticles



With deep learning, we can see the ring corresponding to  $2.35 \text{ \AA}$  atom arrangements

- Significant improvements in spatial resolution on MÖNCH, via deep learning

@ 200 keV	Charge centroid	Deep learning + super resolution		
		Simulation based model	Experiment based model	Knife-edge with experi. model
$\sigma_x$ [pixel]	1.83	0.70	0.60	0.58

- Promising performance for energies lower than 200 keV
- Outlook
  - Detector calibration
  - Simulation development
  - Challenge: large MÖNCH module

# Backup



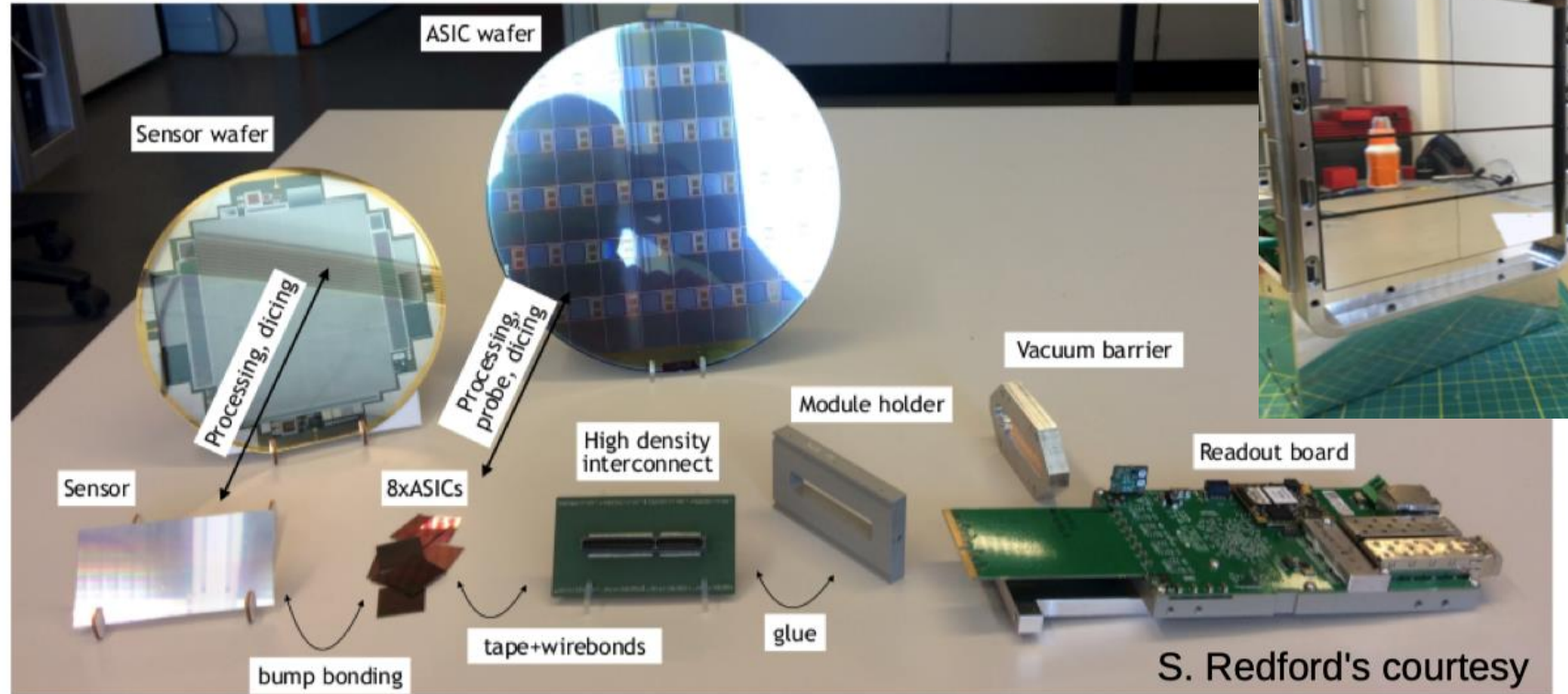
# Design and build detectors in-house

## Work done at PSI:

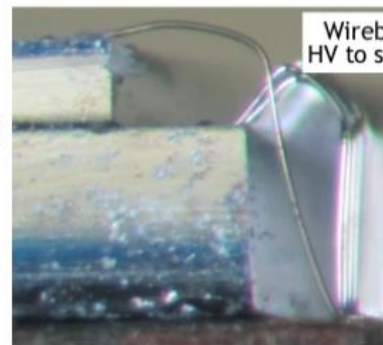
- sensor design
- ASIC design
- readout boards
- flip-chip bonding
- wire-bonding
- mechanics
- assembly
- firmware
- control software

+

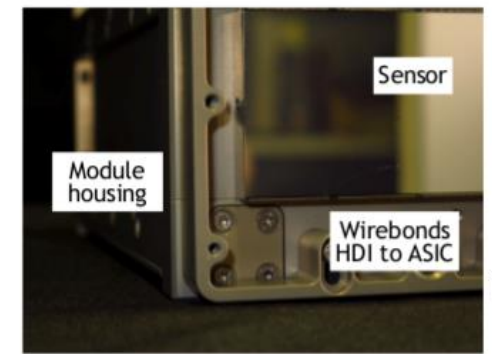
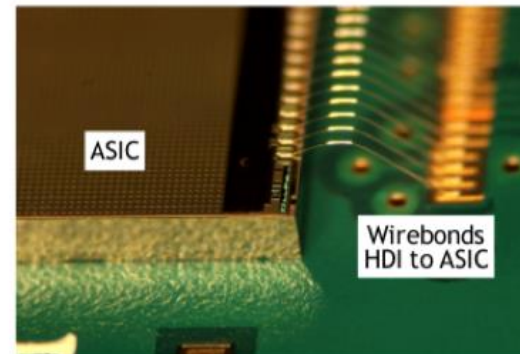
- calibration
- integration/commissioning
- user support/interface



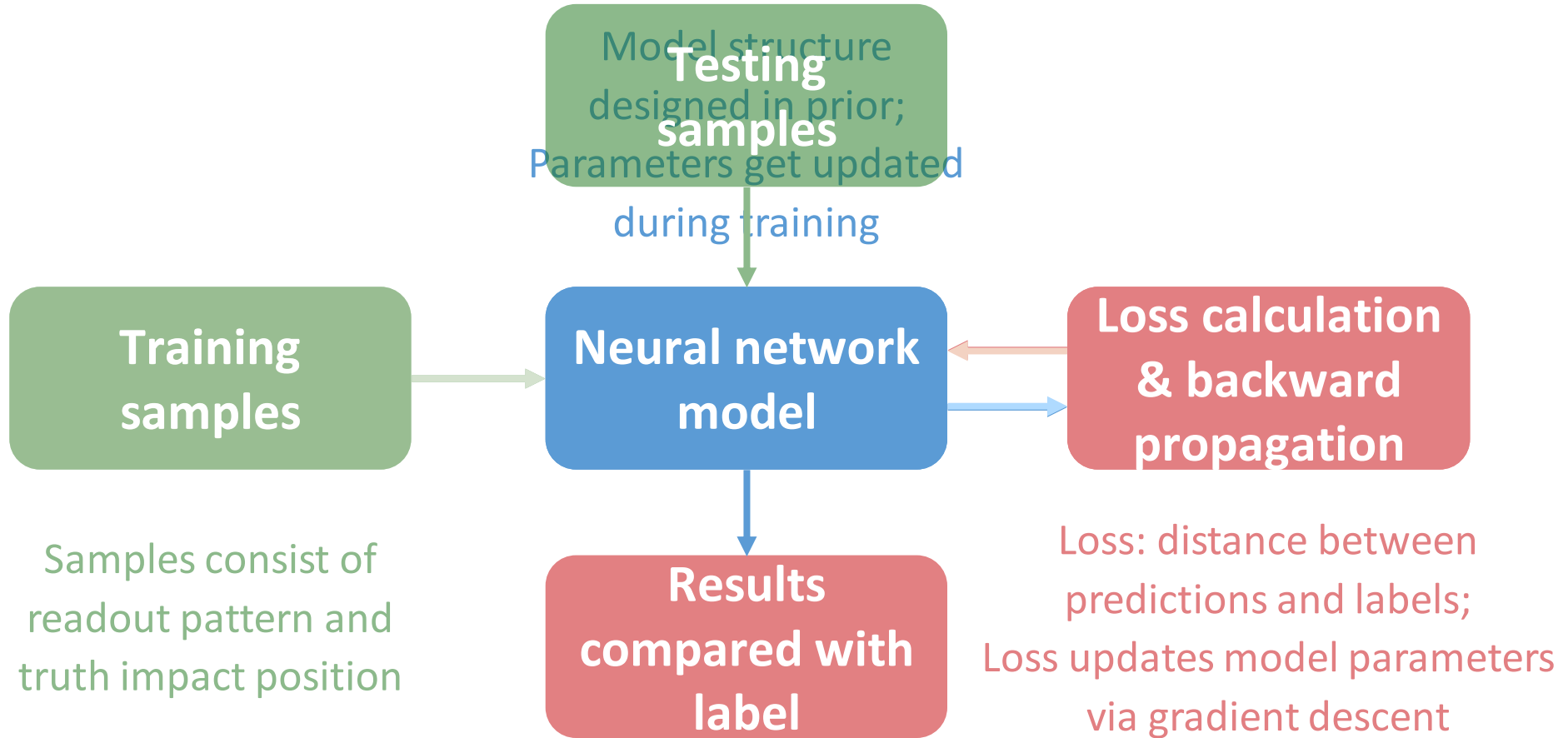
Sensor  
bump bonding  
ASIC



Wirebonds  
HDI to ASIC

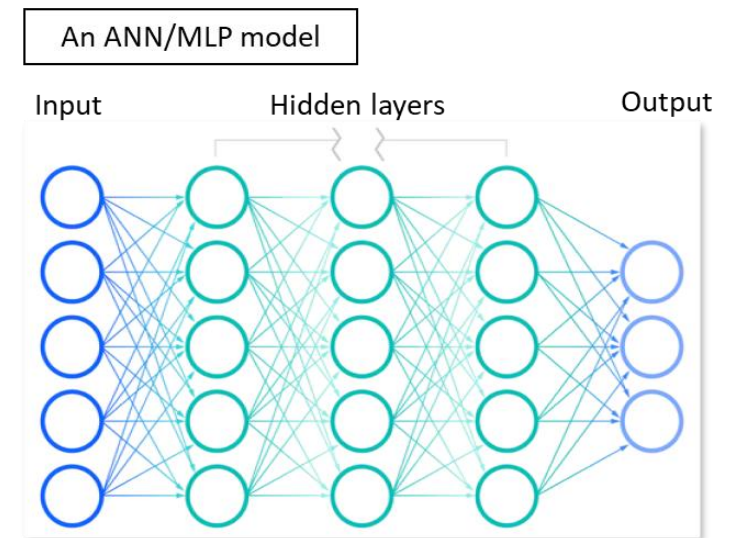
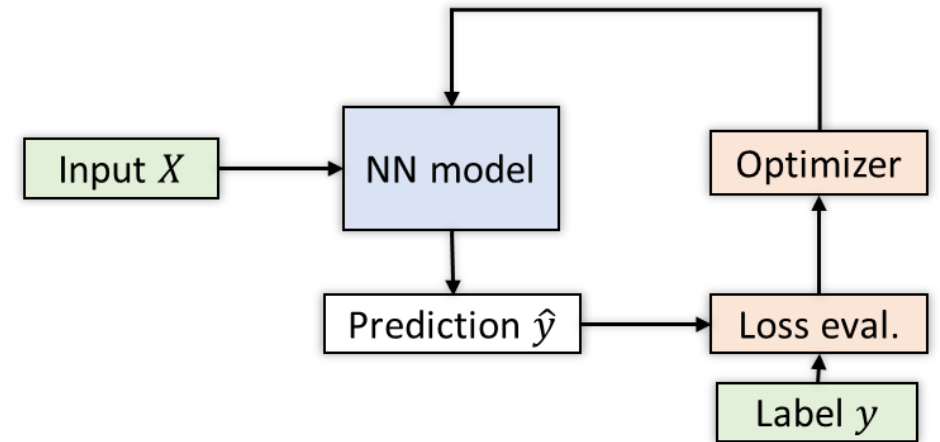


# Deep learning workflow



# Backup Deep learning components

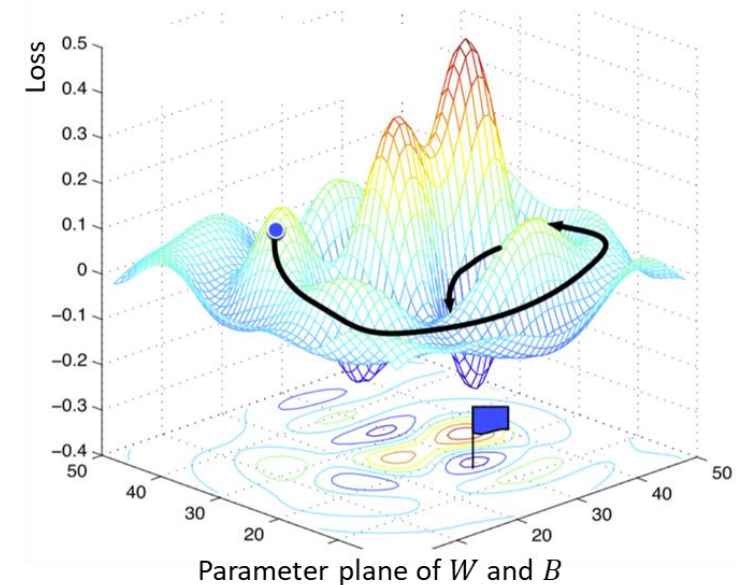
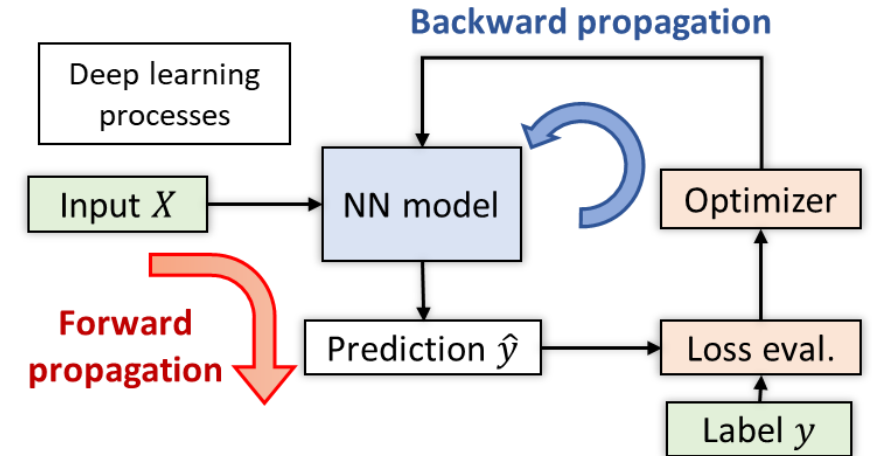
- **Dataset**
  - Inputs  $X$ : signal waveforms, images, texts ...
  - Labels  $y$ : time, position, cat/dog ...
    - Known as ground truth in supervised learning
- **Neural network model**
  - Composes of inter-connected neuron layers
  - Each neuron layer has
    - Weight  $W^{[l]}$ , bias  $B^{[l]}$
    - Activation function  $g$
- **Loss function + optimizer**
  - Loss function  $F$  to evaluate loss  $J$ 
    - $F$ : RMSE, cross-entropy ...
    - $J$ : difference between predictions and labels
  - Optimizer: the pilot to update the model





# Backup: Deep learning training processes

- Forward propagation:
  - $Z^{[l]} = B^{[l]} + W^{[l]}A^{[l-1]}$
  - $A^{[l]} = g(Z^{[l]})$
- Backward propagation:
  - Loss evaluation:  $J = F(\hat{y}, y)$
  - Optimizing:  $W \leftarrow W - \alpha \frac{\partial J}{\partial W}, \frac{\partial J}{\partial W} = \frac{\partial J}{\partial A} \frac{\partial A}{\partial Z} \frac{\partial Z}{\partial W}$ ,  
 $\alpha$ : learning rate, usually  $0.001 < \alpha < 0.1$
- Targets
  - To optimize the model to minimize loss
  - To predict well for untrained data, i.e., good generalization ability



# Backup: CNN kernel

10	10	10	0	0	0
10	10	10	0	0	0
10	10	10	0	0	0
10	10	10	0	0	0
10	10	10	0	0	0
10	10	10	0	0	0

Image in gray scale

\*

1	0	-1
1	0	-1
1	0	-1

Kernel for vertical  
detection

=

0	30	30	0
0	30	30	0
0	30	30	0
0	30	30	0

Results

- Kernel
  - At early stages, CV experts manually designed kernel
  - In ML, dozens of kernels could be automatically formed during training
- Combination of results distinguish pattern in complex images